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(54) METHOD AND INSTRUMENT FOR MEASURING HARDNESS AND ELASTIC MODULUS OF THIN FILM

(57)Abstract:

PROBLEM TO BE SOLVED: To provide a method and instrument for measuring the hardness and elastic modulus of a thin film, capable of accurately and precisely measuring a contact area by merely calculating work without generating a measuring error and capable of accurately evaluating the mechanical characteristics (hardness and elastic modulus) of the thin film.

SOLUTION: In the method and apparatus for measuring the hardness and elastic modulus of the thin film, by pressing a pressure element to the thin film to be measured to change load quasi-statically, an x-value is calculated from a work W_t applied to the thin film of the pressure element at the loading time and a work W applied to the pressure element of the thin film at the unloading time by equation (3). $H/E=0.215-0.234x$ ($0 \leq x \leq 0.8$)...(1) $=0.16-0.16x$ ($0.8 \leq x \leq 1.0$)...(2) $x=(W_t-W_u)/W_t$...(3) $H=P_{max}/A$...(4) $E=(\pi/2A)^{1/2}dP/dh$...(5) Based on the x-value, H/E ratio is calculated from equation (1) or (2) and the contact area A is calculated from the H/E ratio and equations (4), (5) [where, H is hardness (Gpa) of the thin film, E is elastic modulus (Gpa) of the thin film, P is the maximum load (load at the maximum displacement), A is the contact area of the pressure element at the maximum load, h is the displacement of the pressure element (push-in depth) and dP/dh is the inclination of an unloading curve at the maximum load] and are substituted in the equations (4), (5) to calculate the hardness and elastic modulus of the thin film.

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